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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10079094	FILING DATE 02/19/2002	CLASS 029	SUBCLASS	GAU 3729	EXAMINER
**APPLICANTS: Kurihara Hiroyuki; Nakamura Ichiro; Ogura Taketsugu; Shimizu Motohiro;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 2001-042156 02/19/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO P/1071-1538	
Verified and Acknowledged Examiners's initials					
TITLE : Conductive paste, method of controlling viscosity thereof an delectronic component using the same					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for 0.6
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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